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Part Number: [0739425000](#)
Status: **Active**
Overview: [HDM® Backplane Connector System](#)
Description: HDM Board-to-Board Backplane Header, Vertical, Solder Tail, Open End, 144 Circuits

Documents:

[3D Model](#) [Packaging Specification PK-70873-0818 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
 UL E29179

General

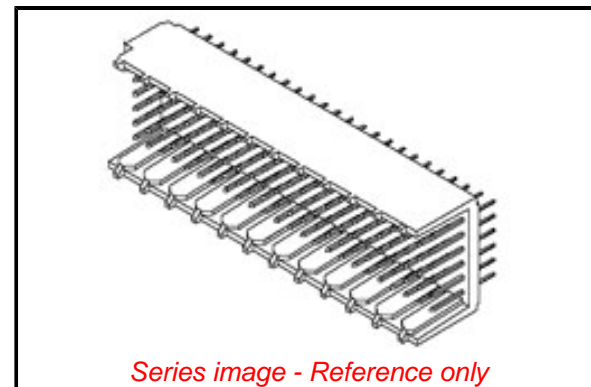
Product Family Backplane Connectors
 Series [73942](#)
 Application Backplane
 Comments Solder Tail
 Component Type PCB Header
 Overview [HDM® Backplane Connector System](#)
 Product Name HDM®
 UPC 800753935020

Physical

Circuits (Loaded) 144
 Circuits (maximum) 144
 Color - Resin Black, Natural
 Durability (mating cycles max) 250
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part No
 Keying to Mating Part None
 Material - Metal Phosphor Bronze
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 Net Weight 6.273/g
 Number of Columns 24
 Number of Pairs Open Pin Field
 Number of Rows 6
 Orientation Vertical
 PC Tail Length 3.00mm
 PCB Locator No
 PCB Retention None
 PCB Thickness - Recommended 2.50mm
 Packaging Type Tube
 Pitch - Mating Interface 2.00mm
 Pitch - Termination Interface 2.00mm
 Plating min - Mating 0.762µm
 Plating min - Termination 2.540µm
 Stackable Yes
 Surface Mount Compatible (SMC) Yes
 Temperature Range - Operating -55°C to +105°C
 Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 1.0A



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Not Contained Per
 -ED/01/2017 (12
 January 2017)

Halogen-Free

Status

Low-Halogen

**Need more information on product
 environmental compliance?**

Email productcompliance@molex.com
 Please visit the [Contact Us](#) section for any
 non-product compliance questions.

China ROHS Green Image
 ELV Not Relevant
 RoHS Phthalates Not Contained

Search Parts in this Series

[73942](#) Series

Mates With

[73632](#) HDM+ Board-to-Board Daughtercard
 Receptacle. [73780](#) HDM Board-to-Board
 Daughtercard Receptacle

Data Rate	1.0 Gbps
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	040
Lead-free Process Capability	SMC&WAVE
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260

Material Info**Reference - Drawing Numbers**

Packaging Specification	PK-70873-0818
Sales Drawing	SD-73942-001

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